2-Input NOR Gate

The NL17SZ02 is a single 2-input NOR Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

Features

- Tiny SOT-353 and SOT-553 Packages
- 2.4 ns T_{PD} at 5 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ02P5X, TC7SZ02FU and TC7SZ02AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

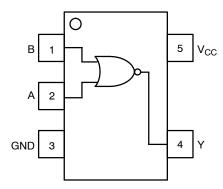


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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MARKING DIAGRAMS

SOT-353/SC70-5/SC-88A **DF SUFFIX CASE 419A**



L3 = Specific Device Marking

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)



XV5 SUFFIX CASE 463B



L3 = Specific Device Marking

= Date Code

PIN ASSIGNMENT

Pin	Function
1	А
2	В
3	GND
4	Y
5	V _{CC}

FUNCTION TABLE

Inp	out	Output Y = A + B
Α	В	Y
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parame	eter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V	
I _{IK}	DC Input Diode Current		-50	mA
I _{OK}	DC Output Diode Current		-50	mA
I _{OUT}	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10	260	°C	
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
P_{D}	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	Class Z Class A N/A	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below	v GND at 125°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

- 3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	1.65	5.5	V
V _{IN}	DC Input Voltage	0	5.5	٧
V _{OUT}	DC Output Voltage	0	5.5	٧
T _A	Operating Temperature Range	-55	+125	°C
t _r , t _f	Input Rise and Fall Time $ V_{CC} = 3.0 \text{ V} \pm 0.3 \\ V_{CC} = 5.0 \text{ V} \pm 0.5 $	V 0 V 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	Т,	_A = 25°C		-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{ОН}	High-Level Output Voltage V _{IN} = V _{IL} or V _{IH}	$I_{OH} = 100 \ \mu\text{A}$ $I_{OH} = -3 \ \text{mA}$ $I_{OH} = -8 \ \text{mA}$ $I_{OH} = -12 \ \text{mA}$ $I_{OH} = -16 \ \text{mA}$ $I_{OH} = -24 \ \text{mA}$ $I_{OH} = -32 \ \text{mA}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.52 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{OH}	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ mA$ $I_{OL} = 8 \ mA$ $I_{OL} = 12 \ mA$ $I_{OL} = 16 \ mA$ $I_{OL} = 24 \ mA$ $I_{OL} = 32 \ mA$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55		0.1 0.24 0.3 0.4 0.4 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			± 0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0			1		10	μΑ
Icc	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 3.0 ns

			V_{CC} $T_A = 25^{\circ}C$ $-55^{\circ}C \le T_A \le 12^{\circ}C$		T _A = 25°C		_A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Propagation Delay	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	1.65	2.0	5.3	11.5	2.0	12.0	ns
t _{PHL}	(Figure 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8	2.0	4.4	9.5	2.0	10.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	0.8	2.9	6.5	0.8	7.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	3.3 ± 0.3	0.5	2.3	4.5	0.5	4.7	
		R_L = 500 Ω , C_L = 50 pF		1.5	2.9	5.0	1.5	5.2	
		R_L = 1 M Ω , C_L = 15 pF	5.0 ± 0.5	0.5	1.9	3.9	0.5	4.1	
		R_L = 500 Ω , C_L = 50 pF		0.8	2.4	4.3	0.8	4.5	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	>4	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF
	(Note 6)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	30	

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

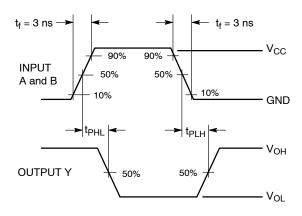
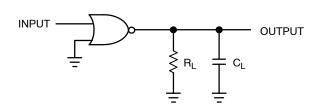


Figure 3. Switching Waveform



A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SZ02DFT2G	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NLV17SZ02DFT2G*	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NL17SZ02XV5T2G	SOT-553 (Pb-Free)	4000 / Tape & Reel

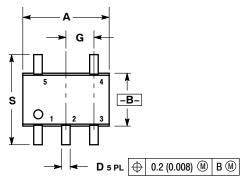
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

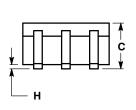
^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

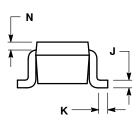
PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353)

CASE 419A-02 ISSUE L







- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

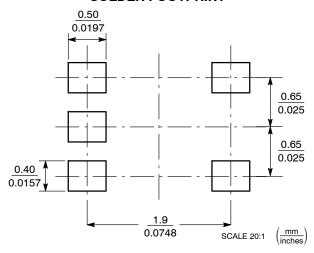
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
C	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	0.026 BSC		BSC	
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008	REF	0.20 REF		
S	0.079	0.087	2.00	2.20	

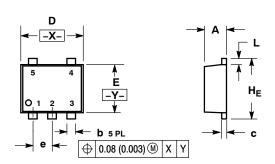
SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553 **XV5 SUFFIX** CASE 463B **ISSUE B**



- NOTES:

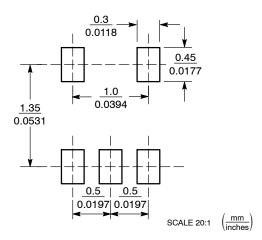
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETERS

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
е		0.50 BSC		0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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